

# Product and Process Change Notice

<b>PCN No.</b>	PCN02996	<b>PCN Date</b>	1/22/2018	<b>Effective Date</b>	4/23/2018
<b>Title</b>	<b>Qualification of ChipMOS as an Assembly Site for DFN small flag Package</b>				

### Type: Major Change

Everspin is adding ChipMOS as a qualified assembly site for the DFN small flag package for SPI interface products.

### Reason For Change

To increase capacity and improve supply flexibility.

### Affected Products

Part Number	Description	Part Number	Description
MR20H40CDF	Industrial Temp.	MR20H40CDFR	Industrial Temp., T&R
MR25H40CDF	Industrial Temp.	MR25H40CDFR	Industrial Temp., T&R
MR25H40VDF	Extended Temp.	MR25H40VDFR	Extended Temp., T&R
MR25H40MDF	Automotive Grade 1	MR25H40MDFR	Automotive Grade 1, T&R
MR25H10CDF	Industrial Temp.	MR25H10CDFR	Industrial Temp., T&R
MR25H10MDF	Automotive Grade 1	MR25H10MDFR	Automotive Grade 1, T&R
MR25H256CDF	Industrial Temp.	MR25H256CDFR	Industrial Temp., T&R
MR25H256MDF	Automotive Grade 1	MR25H256MDFR	Automotive Grade 1, T&R
MR25H256ACDF	Industrial Temp.	MR25H256ACDFR	Industrial Temp., T&R
MR25H256AMDF	Automotive Grade 1	MR25H256AMDFR	Automotive Grade 1, T&R
MR25H256APDF	Automotive Grade 3	MR25H256APDFR	Automotive Grade 3, T&R
MR25H128ACDF	Industrial Temp.	MR25H128ACDFR	Industrial Temp., T&R
MR25H128APDF	Automotive Grade 3	MR25H128APDFR	Automotive Grade 3, T&R
MR25H128AMDF	Automotive Grade 1	MR25H128AMDFR	Automotive Grade 1, T&R

### Impact on Form, Fit, Function, Quality or Reliability

No impact

### Proposed First Ship Date for Change:

April 23, 2018

### Key Material Differences

Material	Site	
	ChipMos	Amkor
Mold Compound	SUMITOMO EME-G631H	SUMITOMO EME-G700
BLT1 Epoxy	Hitachi 4900GC	Sumitomo CRM-1085A
BLT2 Epoxy	EM-710	Henkel ATB-120A DAF
BLT3 Epoxy	Henkel QMI550	Henkel Ablebond 8900NC

### Product Identifier

Assembly site code = H for ChipMOS Taiwan

### Supplier Qual Plan Schedule and Results

ChipMOS assembly line qualification is complete and all Everspin requirements met; a qualification report is available on request.

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### Date Qualification Samples Are Available:

Samples are generally available now but please request your specific part number to your Everspin Sales contact.

### Acceptance of Change

Everspin will consider this change accepted unless specific conditions for acceptance are provided in writing within 30 days of receipt of this notice.

<b>Contact Information</b>		<b>Sample Information</b> <input checked="" type="checkbox"/> <b>Samples Available Now</b>
Joe O'Hare Director, Product Marketing Everspin Technologies <a href="mailto:joe.ohare@everspin.com">joe.ohare@everspin.com</a> (512) 828-3357		Contact Everspin sales: <a href="http://www.everspin.com/contact-us-everspin-technologies">http://www.everspin.com/contact-us-everspin-technologies</a> If using the on-line sample request please refer to this PCN # to receive samples.
<b>Originator</b>		
<u>Date</u> 1/22/2018	<u>Title</u> Marketing Director	<u>Name</u> Joe O'Hare 
<b>Approval and Release</b>		
<u>Date</u> 1/22/2018	<u>Title</u> Quality Engineer	<u>Name</u> Paul Drobny
<u>Date</u> 1/22/2018	<u>Title</u> VP of Sales	<u>Name</u> Annie Flaig
<u>Date</u> 1/22/2018	<u>Title</u> VP of Operations	<u>Name</u> Norm Armour